



Material Content Data Sheet



Sales Product Name				SAK-C164CI-8EM CB		Issued		29. August 2013	
MA#				MA001053004					
Package				PG-MQFP-80-7		Weight*		995.30 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	43.021	4.32	4.32	43225	43225	
leadframe	non noble metal	magnesium	7439-95-4	0.375	0.04		376		
	inorganic material	silicon	7440-21-3	1.624	0.16		1631		
	non noble metal	nickel	7440-02-0	7.494	0.75		7530		
	non noble metal	copper	7440-50-8	240.318	24.15	25.10	241454	250991	
wire	noble metal	gold	7440-57-5	4.075	0.41	0.41	4094	4094	
encapsulation	organic material	carbon black	1333-86-4	2.024	0.20		2033		
	plastics	epoxy resin	-	85.672	8.61		86076		
	inorganic material	silicondioxide	60676-86-0	586.884	58.96	67.77	589657	677766	
leadfinish	non noble metal	tin	7440-31-5	9.487	0.95	0.95	9532	9532	
plating	noble metal	silver	7440-22-4	7.024	0.71	0.71	7057	7057	
glue	plastics	acrylic resin	-	1.460	0.15		1467		
	noble metal	silver	7440-22-4	5.841	0.59	0.74	5868	7335	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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